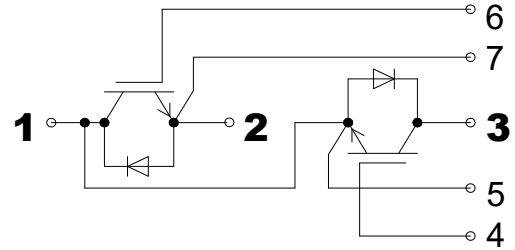


# SGG150NF120UC2

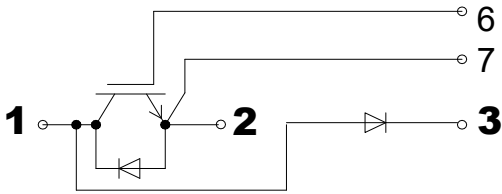
## IGBT Modules



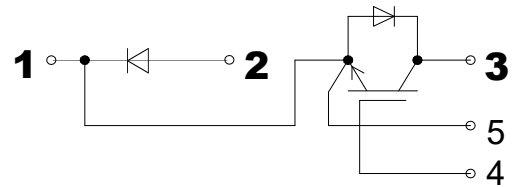
**SGG150NF120UC2**



**SGD150NF120UC2**



**SDG150NF120UC2**



Symbol	Test Condition	Value	Unit
<b>IGBT</b>			
V <sub>CES</sub>		1200	V
I <sub>C</sub>	T <sub>C</sub> = 100°C per chip	150	A
V <sub>GES</sub>		±20	V
T <sub>vj</sub> (T <sub>stg</sub> )		-40 ~ +150(125)	°C
P <sub>tot</sub>		500	W
<b>INVERSE DIODE</b>			
I <sub>F</sub>	T <sub>C</sub> =25°C per chip	150	A
I <sub>FM</sub>		300	A
V <sub>RRM</sub>		1200	V
i <sup>2</sup> <sub>t</sub>	T <sub>j</sub> =125°C, t=10ms, V <sub>R</sub> =0V	4600	A <sup>2</sup> S

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# SGG150NF120UC2

## IGBT Modules

Symbol	Test Conditions	Min	Typ	Max	Unit
<b>IGBT</b> <span style="float: right;"><b>Tc = 25°C unless otherwise specified</b></span>					
V <sub>GE(th)</sub>	V <sub>GE</sub> =V <sub>C</sub> E, I <sub>C</sub> = 1mA	4.5	5.5	6.7	V
I <sub>CES</sub>	V <sub>GE</sub> = 0; V <sub>C</sub> E=V <sub>C</sub> ES; T <sub>j</sub> =25(125)°C			1	mA
V <sub>C</sub> E(TO)	T <sub>j</sub> =25(125)°C		1.0(0.9)	1.2(1.1)	V
r <sub>C</sub> E	V <sub>GE</sub> =15V		9(12)	12(15)	mΩ
V <sub>C</sub> E(sat)	I <sub>C</sub> =150A; V <sub>GE</sub> =15V; chip level		2.1	2.5	V
C <sub>ies</sub>	V <sub>GE</sub> =0V, V <sub>C</sub> E=25V, f=1MHz		9.20		nF
C <sub>oes</sub>			1.00		
C <sub>res</sub>			0.93		
L <sub>C</sub> E				29	nH
RCC'+EE'	Terminal to Case, Tc=25°C		0.75		mΩ
t <sub>d(on)</sub>	V <sub>CC</sub> = 600V, I <sub>C</sub> = 150A R <sub>GO</sub> N = R <sub>GO</sub> FF = 10Ω T <sub>j</sub> =125°C V <sub>GE</sub> =±15V		185		ns
t <sub>r</sub>			50		ns
t <sub>d(off)</sub>			590		ns
t <sub>f</sub>			50		ns
E <sub>on</sub> /E <sub>off</sub>				11.50/9.30	
<b>INVERSE DIODE</b> <span style="float: right;"><b>Tc = 25°C unless otherwise specified</b></span>					
V <sub>F</sub>	I <sub>F</sub> = 150A; V <sub>GE</sub> =0V; T <sub>j</sub> = 25°C		2.0	2.5	V
Q <sub>rr</sub>	I <sub>F</sub> =150A; V <sub>R</sub> =300V; T <sub>j</sub> =25°C di/dt = 3500A/us, V <sub>GE</sub> =-15V		14.5		μC
I <sub>RRM</sub>			130		A
E <sub>rec</sub>			4.80		mJ
<b>THERMAL CHARACTERISTICS</b>					
R <sub>th(j-c)</sub>	per IGBT			0.125	K/W
R <sub>th(j-c)D</sub>	per FRD			0.550	K/W
R <sub>th(c-s)</sub>	per module			0.101	K/W
M <sub>s</sub>		2.5		4	Nm
Weight			325		g

### Features

- Planar Gate Field Stop (SPT<sup>+</sup>) Technology IGBT
- Fast Recovery Free Wheeling Diode
- Low Switching Losses
- V<sub>ce</sub>(sat) with positive temperature coefficient
- Fast Switching and short tail current
- Switched mode power supplies at f<sub>sw</sub>>20KHz
- Resonant inverters up to 100KHz
- Electronic Welders at f<sub>sw</sub>>20KHz

### Application

- Welding inverters
- Inductive Heating

### Advantages

- Space and weight savings
- Reduced protection circuits

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## IGBT Modules

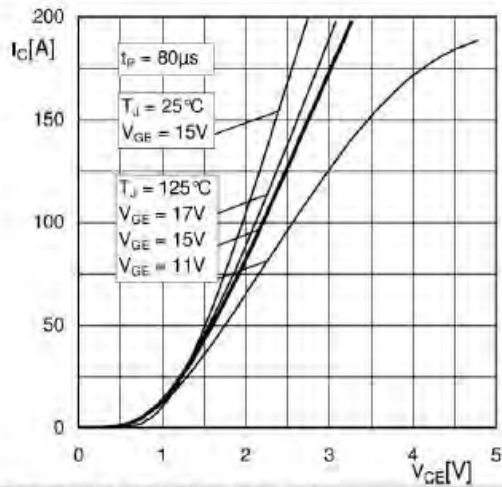


Fig. 1 Typ. output characteristic, inclusive  $R_{CC+EE}$

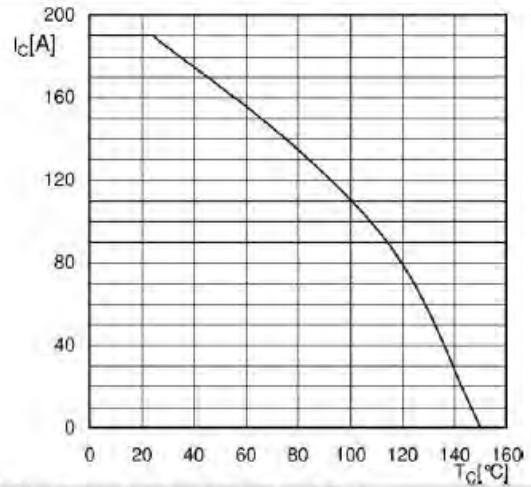


Fig. 2 Rated current vs. temperature  $I_c = f(T_c)$

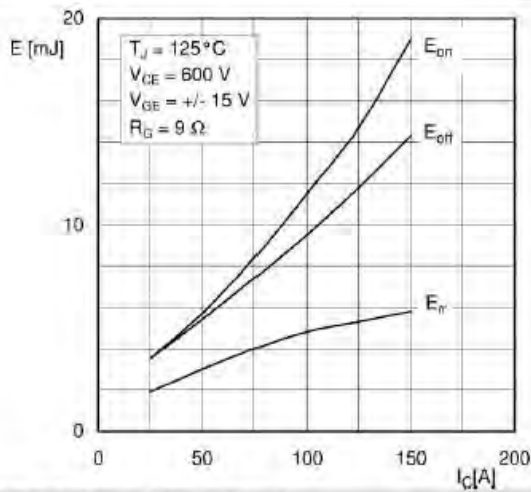


Fig. 3 Typ. turn-on /-off energy =  $f(I_c)$

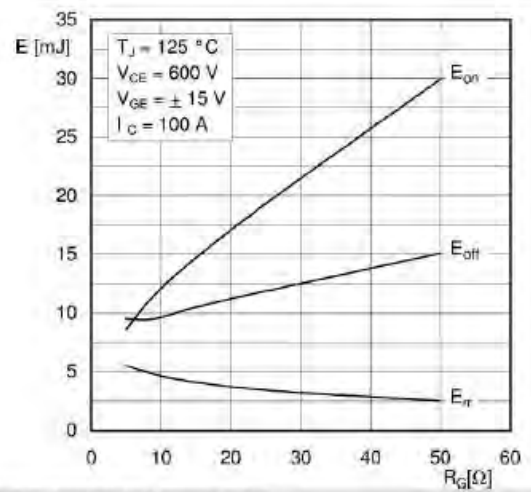


Fig. 4 Typ. turn-on /-off energy =  $f(R_G)$

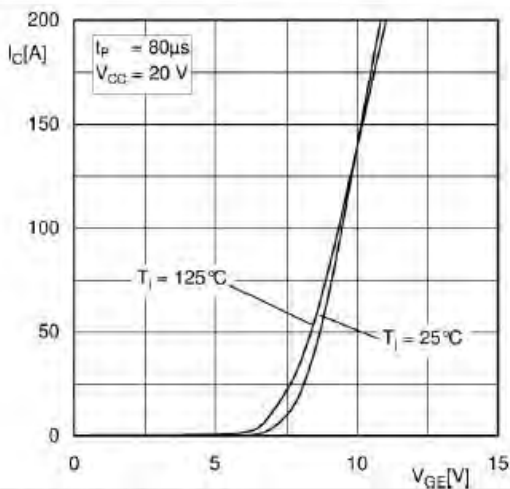


Fig. 5 Typ. transfer characteristic

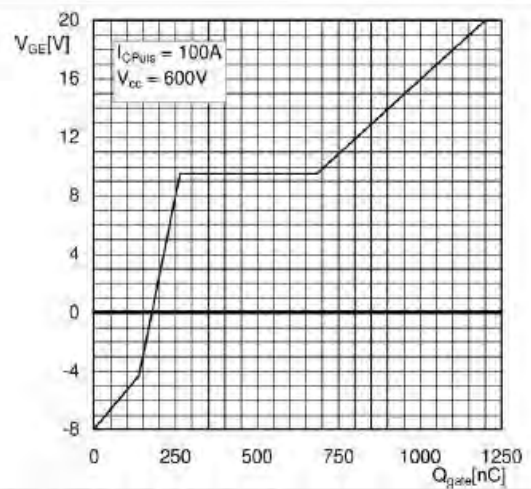


Fig. 6 Typ. gate charge characteristic

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## IGBT Modules

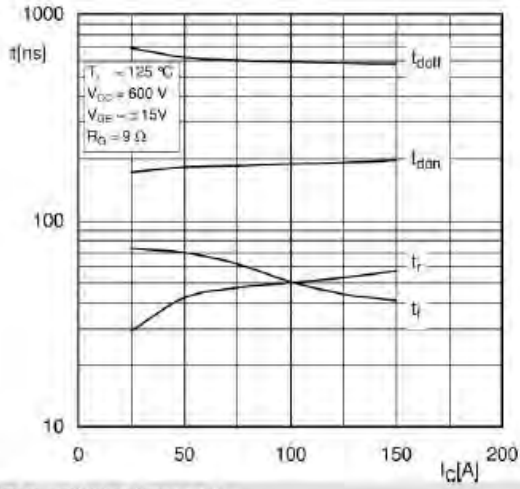


Fig. 7 Typ. switching times vs.  $I_c$

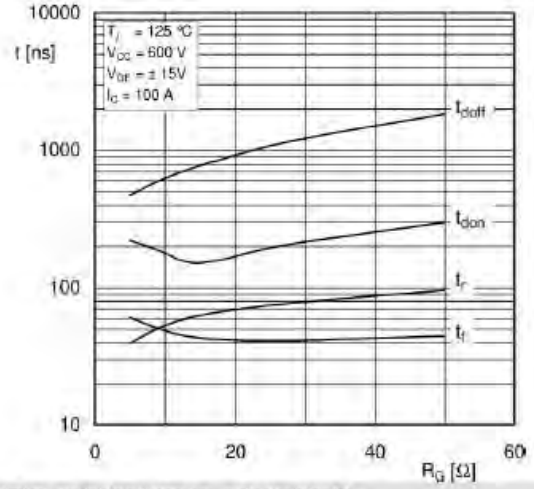


Fig. 8 Typ. switching times vs. gate resistor  $R_g$

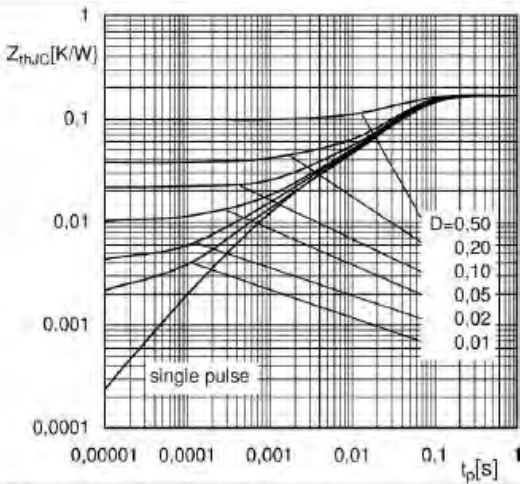


Fig. 9 Transient thermal impedance of IGBT

$$Z_{th(j-c)} = f(t_p); D = \frac{t_p}{t_c} = t_p \cdot f$$

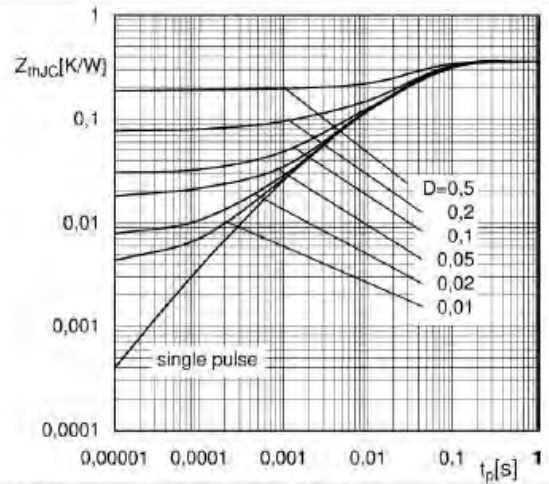


Fig. 10 Transient thermal impedance of FWD

$$Z_{th(j-c)} = f(t_p); D = \frac{t_p}{t_c} = t_p \cdot f$$

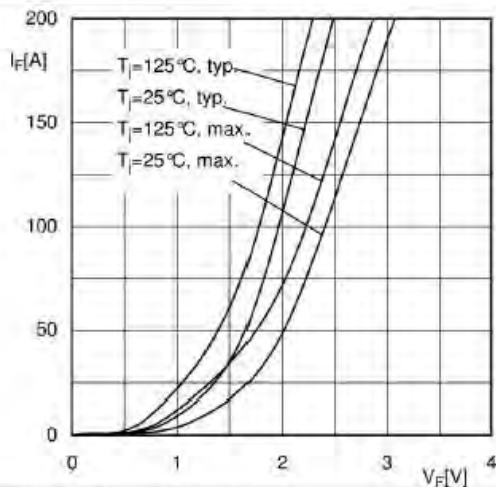


Fig. 11 FWD diode forward characteristic

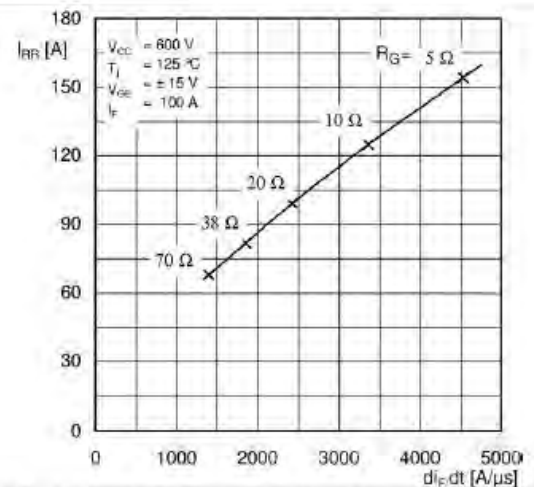
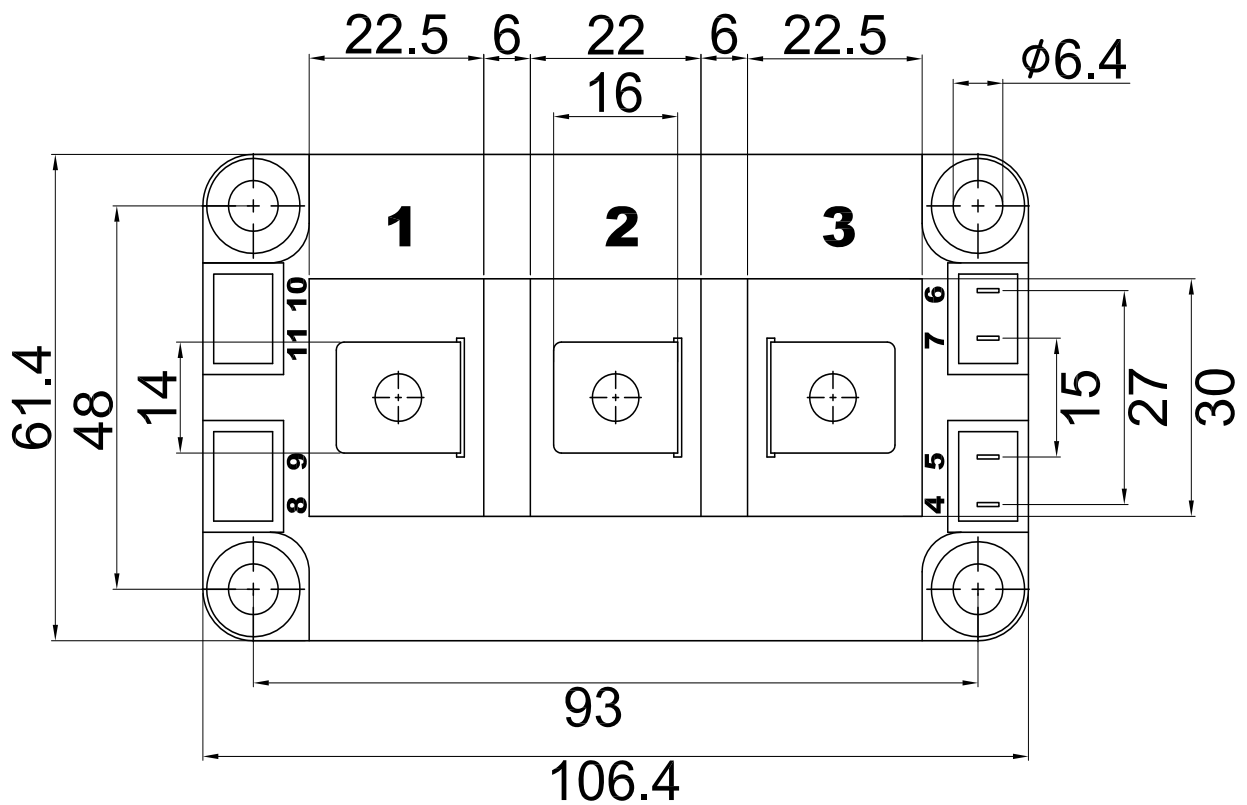
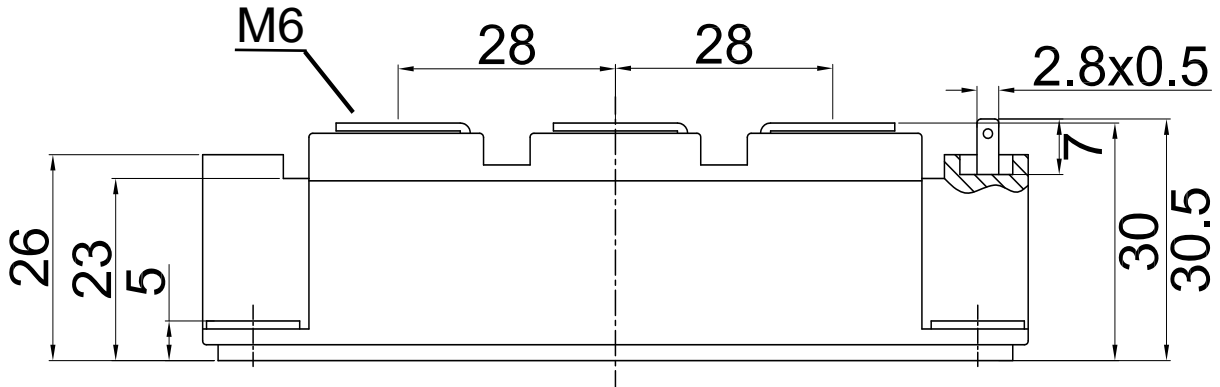


Fig. 12 Typ. FWD diode peak reverse recovery current

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IGBT Modules



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